

Adhesives_Sealants

Weekly Intelligence Report

2026-08-09 | 10 articles | 4 countries

troy-technical.jp

This Week's Keyword

Advanced Adhesives

AI, EV, and M&A Drive Market Shifts

10

articles

Total Articles Analyzed

4

countries

Source Countries

4.5

%

Henkel Adh. Tech Growth

28

x

Mat. Dev. Speedup

All 10 Articles This Week — 5-Axis Evaluation Matrix

How to read columns — Tech Novelty: degree of breakthrough Market Proximity: closeness to commercialization Market Impact: industry-wide effect Data Reliability: quantitative data & peer review US/EU Relevance: direct impact on US/European companies & supply chains

#	Article Title	Type	Tech Novelty	Market Proximity	Market Impact	Data Reliability	US/EU Relevance	Summary
#01	APPLIED Adhesives M&A;	Corporate Strategy						APPLIED Adhesives expands in Europe via acquisition and strengthens US presence with another acquisition and exclusive Henkel distribution.
#02	World Adh. Conf. 2026	Market Overview						World Adhesive & Sealant Conference 2026 to offer industry insights, tech trends, and networking for global professionals.
#03	APPLIED Acquires Van Asperen	Corporate Strategy						APPLIED Adhesives acquired Dutch Van Asperen Kleefstoffen, bolstering its European presence in packaging and labeling.
#04	Henkel Raises Sales Guidance	Corporate Strategy						Henkel raises 2026 sales guidance, driven by 4.5% organic growth in Adhesive Technologies, especially Mobility & Electronics.
#05	Indium Plating-Free Paste	New Product						Indium Corp. unveils plating-free copper sintering paste and Bi-free mid-temp solder for high-power semiconductors, reducing cost and improving sustainability.
#06	Sumitomo Bakelite Sales	Corporate Strategy						Sumitomo Bakelite achieved record ¥305B sales in FY2025, driven by advanced encapsulants for AI training silicon.
#07	Univar Acquires H.M. Royal	Corporate Strategy						Univar Solutions acquired H.M. Royal, expanding its US distribution of rubber, plastic, and adhesive additives.
#08	Emerson Acquires Glue Inc.	Corporate Strategy						Emerson acquired AI-enabled validation and test software innovator Glue Inc. to accelerate its software-defined strategy.
#09	Dexerials Functional Mats.	Corporate Strategy						Dexerials reports solid Q1 FY2026 performance in functional materials like ACF and SVR, accelerating innovation via exhibitions.
#10	Resonac QC Ware Speedup	Research						Resonac and QC Ware achieved a 28x speedup in chemical reaction transition state calculations, dramatically enhancing semiconductor material development.

●●●●○ High ●●●○● Med-High ●●○○○ Med ●○○○○ Low | Yellow highlight = featured article

Three Questions That Demand Your Decision This Week

❶ Is your R&D; leveraging advanced computational chemistry?

Resonac's 28x speedup in chemical calculations (Article #10) signals a paradigm shift in material discovery. Are your R&D; teams equipped with similar AI/quantum-enhanced tools to accelerate new material development, especially for critical semiconductor and EV applications?

❷ Are your semiconductor material suppliers keeping pace with AI/EV demands?

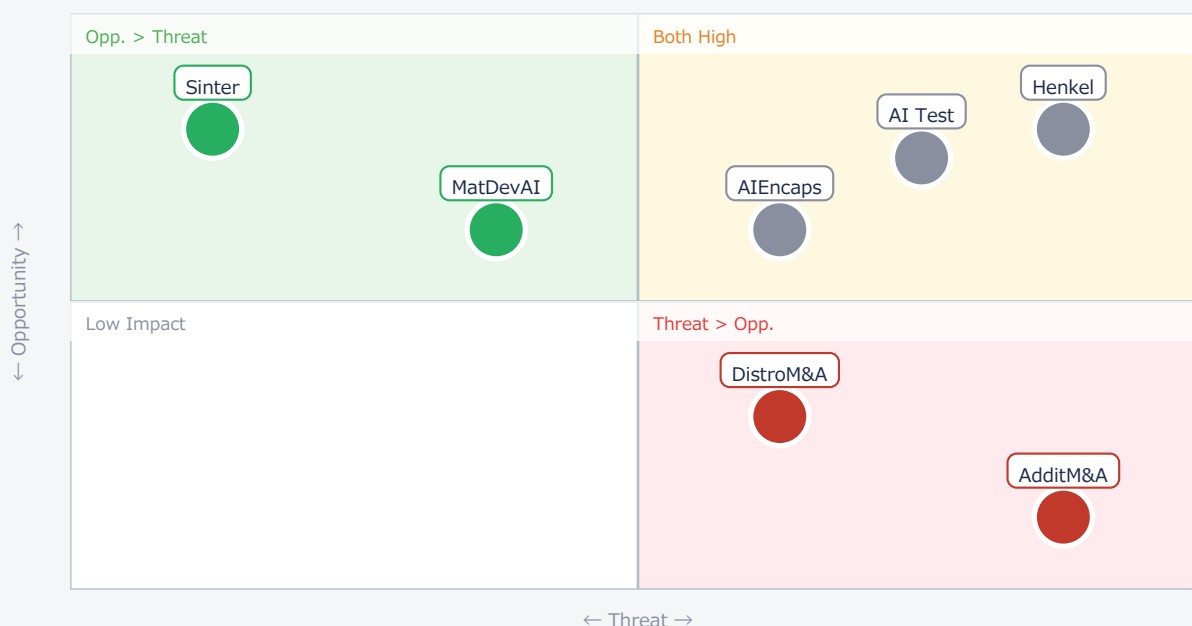
Henkel's strong growth in Mobility & Electronics (Article #04) and Sumitomo Bakelite's record sales from AI encapsulants (Article #06) highlight intense demand. Does your supply chain have access to these high-performance materials, or are you at risk of being outpaced by competitors with superior material access?

❸ How vulnerable is your distribution network to rapid consolidation?

APPLIED Adhesives (Articles #01, #03) and Univar Solutions (Article #07) are actively consolidating the adhesive and additive distribution landscape. Are your procurement strategies robust enough to navigate fewer, larger distributors, ensuring competitive pricing and reliable supply?

Opportunities vs. Threats for US/European Companies

Opportunity vs. Threat Matrix for US/European Companies



Item	Quadrant	↑ Opportunity	↓ Threat
● Sinter	Opp.	Cost/Perf	—
● MatDevAI	Opp.	R&D; Speed	—
● Henkel	Critical	Growth Seg	Comp. Adv.
● AIEncaps	Critical	AI Demand	Asian Domin
● AI Test	Critical	Efficiency	Tech Gap
● DistroM&A;	Threat	Market Share	Consolidat
● AdditM&A;	Threat	US Reach	Comp. Press

Deep Dive ① — Plating-Free Sintering for Power Devices

#05 | 2026/07/30 | Indium Corporation | Tech Novelty ● ● ● ● ○ Proximity ● ● ● ● ○ Market Impact ● ● ● ● ○ Data Reliability ● ● ● ● ○ US/EU Relevance ● ● ● ● ●

Indium Corporation has unveiled a next-gen copper sintering paste that eliminates the need for gold or silver plating in high-power semiconductor applications, alongside a lead-free, bismuth-free mid-temperature solder. This innovation promises high reliability and strong bonds while significantly reducing manufacturing costs and simplifying processes for advanced electronics.

The plating-free approach addresses critical demands for cost reduction and supply chain efficiency in high-power devices, crucial for EVs, 5G infrastructure, and AI hardware. The new Bi-free solder also meets stringent environmental regulations, ensuring sustainable and reliable bonding for sensitive components.

► Strategic Analyst's Perspective

Strategic Analyst's Perspective: The claims of plating-free sintering are highly realistic, building on existing sintering technologies but with a significant material science advancement. The primary technical barrier is broad adoption and qualification across diverse semiconductor platforms, which can be lengthy. [Opportunity] for US/EU OEMs and device manufacturers to reduce material costs and simplify assembly processes for high-power modules. [Threat] for existing precious metal plating suppliers. US/EU materials suppliers should evaluate licensing or developing similar plating-free alternatives. [Next Actions]: [R&D;] Initiate evaluation of Indium's samples for next-gen power modules by Q4 2026. [Procurement] Assess potential cost savings and supply chain resilience by Q1 2027.

Deep Dive ② — AI Accelerates Material Discovery 28x

#10 | 2026/08/04 | Resonac (公式ウェブサイト) | Tech Novelty ● ● ● ● ● Proximity ● ● ○ ○ ○ Market Impact ● ● ● ● ● Data Reliability ● ● ● ● ○ US/EU Relevance ● ● ● ● ○

Resonac, in collaboration with QC Ware, has achieved a 28x speedup in chemical reaction transition state calculations using next-generation computational chemistry. This breakthrough dramatically enhances the efficiency of material development, particularly for semiconductor materials, by shortening discovery and optimization timelines.

This acceleration allows researchers to explore vastly more compounds and reaction pathways, potentially completing calculations that once took months in mere days. It is critical for developing novel dielectric materials, interconnects, and encapsulants needed for miniaturization and enhanced performance in advanced semiconductors.

► Strategic Analyst's Perspective

Strategic Analyst's Perspective: The 28x speedup is a significant academic breakthrough, likely validated under specific, optimized conditions. The challenge lies in generalizing this efficiency to a wide array of complex industrial material development problems and integrating it into existing R&D; workflows. [Opportunity] for US/EU materials and chemical companies to dramatically accelerate their R&D; cycles, gain first-mover advantage in new material discovery, and reduce development costs. [Threat] for companies relying solely on traditional experimental 'trial and error' methods, risking being outpaced by digitally advanced competitors. [Next Actions]: [R&D;] Form a task force to investigate AI/quantum computing partnerships for computational chemistry by Q4 2026. [Strategy] Allocate budget for advanced materials informatics tools and training by Q1 2027.

Deep Dive ③ — AI Silicon Drives Encapsulant Market

#06 | 2026/08/05 | The Shashi (住友ベークライトの会社情報を含むサイト) | Tech Novelty●●●○○ Proximity●●●●●
Market Impact●●●●○ Data Reliability●●●○○ US/EU Relevance●●●●○

Sumitomo Bakelite reported record ¥305 billion sales in FY2025, primarily driven by strong demand for its advanced encapsulant materials, especially those used in AI training silicon. The company's focus on application-specific solutions for high-performance computing (HPC) and AI chips has been a key success factor.

These high-performance epoxy molding compounds are crucial for enhancing semiconductor reliability, improving heat dissipation, and enabling miniaturization in demanding AI environments. Sumitomo Bakelite's strategic emphasis on being a solutions provider, rather than just a material supplier, positions it strongly in this rapidly growing market.

► Strategic Analyst's Perspective

Strategic Analyst's Perspective: Sumitomo Bakelite's sales figures are realistic, reflecting the explosive growth in AI and HPC. The technical barrier is continuous innovation to meet ever-increasing demands for thermal management and reliability in next-gen AI chips. [Opportunity] for US/EU materials suppliers to develop competitive advanced encapsulants and thermal interface materials for AI/HPC. [Threat] for US/EU semiconductor manufacturers if they become overly reliant on a limited number of Asian suppliers for critical packaging materials, potentially impacting supply chain resilience and cost. [Next Actions]: [R&D;] Benchmark current encapsulant performance against Sumitomo's offerings for AI/HPC applications by Q4 2026. [Procurement] Diversify supplier base for advanced semiconductor encapsulants and explore regional manufacturing options by Q2 2027.

Other Notable Articles

Henkel Raises 2026 Full-Year Sales Guidance (Henkel (公式プレスリリース))
Tech Novelty●●○○○ Proximity●●●●● Market Impact●●●●○

Henkel's strong adhesive growth, especially in Mobility & Electronics, signals robust demand in key sectors for US/EU OEMs.

APPLIED Adhesives Accelerates Expansion with European and US East Coast M&A; , Plus Exclusive Partnership with Henkel (APPLIED Adhesives)
Tech Novelty●●○○○ Proximity●●●●● Market Impact●●●○○

US-based APPLIED Adhesives' aggressive M&A; and distribution deals reshape the competitive landscape for US/EU distributors.

Emerson Acquires AI-Enabled Validation and Test Software Innovator Glue Inc. to Accelerate Software-Defined Strategy (StockTitan (PR Newswireの転載))
Tech Novelty●●●○○ Proximity●●●●● Market Impact●●●○○

Emerson's acquisition of AI test software highlights the growing importance of AI in manufacturing validation for US/EU industries.

Univar Solutions Acquires H.M. Royal, Expanding Distribution of Rubber, Plastic, and Adhesive Additives Across US (Coatings World)
Tech Novelty●●○○○ Proximity●●●●● Market Impact●●●○○

Further consolidation in US specialty chemical distribution impacts procurement strategies for US/EU manufacturers.

Recommended Actions This Week

Action recommendations based on article evaluation matrix and opportunity/threat analysis.

■ Immediate (this week)

- [R&D;] Evaluate Indium Corp.'s plating-free sintering paste for high-power device roadmaps to assess potential cost and performance benefits.
- [Procurement] Assess supply chain exposure to consolidating adhesive and additive distributors (e.g., APPLIED, Univar) and identify alternative sourcing options.

■ Short-term (1 month)

- [R&D;] Investigate Resonac/QC Ware's computational chemistry methods for accelerating internal material R&D;, potentially through pilot projects or academic partnerships.
- [Strategy] Analyze Henkel's and Sumitomo Bakelite's growth in Mobility & Electronics and AI encapsulants to benchmark market share, innovation, and identify competitive gaps.
- [Business Dev] Explore strategic partnerships or M&A; opportunities in advanced functional materials for AI and EV applications.

■ Medium-long term (quarter+)

- [R&D;] Develop internal expertise or strategic partnerships in AI-driven material discovery and quantum chemistry to maintain long-term competitive advantage.
- [Executive] Review M&A; targets in specialty adhesives/functional materials to counter market consolidation and secure critical supply chains for future growth.
- [Legal/IP] Conduct a landscape analysis of IP in plating-free sintering and AI-driven material design to inform future R&D; and acquisition strategies.

troy-technical.jp/en | Original curation. Article copyrights belong to respective authors. | Gemini API + Claude | 2026-08-09

Adhesives_Sealants — Selected Articles

Date: 2026-08-09

Articles: 10

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- #13 Resonac and QC Ware Collaboration Achieves 28x Speedup in Chemical Reaction Transition State Calculations, Dramatically Enhancing Semiconductor Material Development Efficiency

#01 APPLIED Adhesives Accelerates Expansion with European and US East Coast M&A, Plus Exclusive Partnership with Henkel

Published August 06, 2026 APPLIED Adhesives USA



OVERVIEW

APPLIED Adhesives expanded its European presence by acquiring Van Asperen Kleefstoffen in the Netherlands and strengthened its US East Coast silicone solutions through the acquisition of Industrial Sales and Distribution (ISD). Additionally, the company was named the exclusive US distributor for Henkel's flexible packaging technologies, significantly enhancing its offerings in the packaging market. These strategic moves accelerate its global business expansion and comprehensive solution delivery to customers.

Key Findings

APPLIED Adhesives is significantly accelerating its business expansion by simultaneously achieving entry into the European market, strengthening its presence on the US East Coast, and expanding its offerings in the packaging market, all through a series of strategic acquisitions and partnerships. These moves solidify the company's position as a leading provider of adhesive and related solutions.

Technical / Clinical Details

The main strategic developments announced by APPLIED Adhesives are as follows:

- **European Expansion with Van Asperen Kleefstoffen Acquisition:** APPLIED Adhesives acquired Van Asperen Kleefstoffen, an adhesive solutions provider based in the Netherlands. This marks the company's first acquisition in the Netherlands and its second in Europe. Van Asperen is a premium partner of Henkel and 3M, having supplied high-quality adhesive solutions for the packaging, labeling, and paper converting markets. This acquisition provides APPLIED Adhesives with a strong foothold in the European market, substantially enhancing its regional service capabilities.
- **US East Coast Reinforcement with Industrial Sales and Distribution (ISD) Acquisition:** APPLIED Adhesives acquired Industrial Sales and Distribution (ISD), a distributor of adhesives and silicones. ISD offers technical expertise and specialized solutions in the aerospace, product assembly, and pad printing markets. This acquisition expands APPLIED Adhesives' silicone solutions portfolio and strengthens its market coverage and expertise in the US East Coast region.
- **Exclusive US Distribution Partnership for Henkel Flexible Packaging Technologies:** APPLIED Adhesives has been designated as the exclusive US distributor for Henkel's packaging adhesives business. This partnership aims to strengthen APPLIED Adhesives' presence in the flexible packaging market and provide Henkel's innovative adhesive and coating technologies to US converters. The collaboration focuses on applications such as food and beverage, health and beauty, and pet products, addressing needs for high performance, regulatory compliance, and sustainability.

These integrated strategies enable the provision of comprehensive product and technical support to customers, establishing a competitive advantage in each market.

Background & Context

The adhesive and sealant market is becoming increasingly competitive amidst accelerating globalization and industrial consolidation. Companies are actively pursuing strategic acquisitions and partnerships to expand market share and deepen expertise in specific technological areas or regions. Particularly in growth markets like packaging, aerospace, and electronics, there is rising demand for high-performance and environmentally friendly adhesive solutions, requiring suppliers to expand their product portfolios and service networks. APPLIED Adhesives' series of actions reflect these industry trends.

Strategic Significance & Outlook

APPLIED Adhesives' strategic initiatives are poised to elevate the company into a major global player in the adhesive market. The full-scale entry into the European market, the strengthening of silicone solutions on the US East Coast, and the establishment of leadership in the packaging market through the partnership with Henkel will further accelerate the company's growth trajectory. This will enable the company to provide more customers with localized, specialized support and a broad range of high-performance adhesive solutions, contributing to customer innovation and productivity improvements across diverse industrial sectors. Moving forward, the company is likely to focus on expanding its market share in existing markets while also exploring new geographical regions and application areas.

Source: <https://www.appliedadhesives.com/category/press-release/>

#03 World Adhesive & Sealant Conference 2026 to Deliver Industry Insights and Networking over Three Days

Published September 01, 2026 World Adhesive & Sealant Conference International



OVERVIEW

The World Adhesive & Sealant Conference 2026 is a three-day event bringing together global leaders, researchers, and engineers in the adhesive and sealant industry. Through plenary sessions, breakout sessions, an EXPO, and networking social events, attendees will gain deep insights into the latest market trends, technological innovations, and regulatory developments, fostering interactions with experts. The conference aims to contribute to the sustainable growth and advancement of the industry.

Key Findings

The 'World Adhesive & Sealant Conference 2026' will be held as a premier global event, gathering adhesive and sealant industry professionals to discuss the latest technological trends, market strategies, and regulatory frameworks. This three-day conference is focused on fostering industry innovation and maximizing knowledge sharing and networking among participants.

Technical / Clinical Details

The conference is set to cover a broad range of cutting-edge topics in the adhesive and sealant sector. Key session contents include:

- **Plenary Sessions:** Leading industry thinkers and executives will provide high-level insights into macroeconomic trends, global market challenges, and future opportunities facing adhesive and sealant technologies. Discussions will particularly focus on the impact of environmental regulations, sustainability, and digitalization on the industry.
- **Breakout Sessions:** These sessions will focus on more specialized themes, detailing technological advancements such as:
 - **High-Performance Adhesives:** Next-generation structural, thermally conductive, and electrically conductive adhesives contributing to automotive lightweighting, miniaturization of electronic components, and improved energy efficiency in buildings.
 - **Eco-Friendly Sealants:** Solutions aimed at reducing environmental footprint, including low-VOC, bio-based, and recyclable material sealants.
 - **Smart Adhesive Technologies:** Products with new functionalities such as sensing capabilities, self-healing adhesives, and debonding-on-demand adhesives.
 - **Manufacturing and Application Automation:** Technologies for optimizing production processes, including precise adhesive application, robotic automation, and AI utilization for quality control.

- **EXPO:** Leading adhesive and sealant manufacturers, raw material suppliers, and equipment manufacturers will showcase their latest products and technologies. This allows attendees to evaluate concrete solutions by seeing and interacting with actual products.

These sessions provide valuable opportunities for engineers, researchers, and business development personnel to gain practical insights and strategic perspectives.

Background & Context

The adhesive and sealant industry is continuously growing, driven by increasing demands for lightweighting, joining dissimilar materials, enhanced durability in manufacturing, and sustainability. The global market is propelled by demand from diverse end-use industries, including automotive, building and construction, packaging, electronics, and medical. In this context, understanding new technological trends and building international collaborations is essential for companies to maintain competitiveness and seize future growth opportunities.

Strategic Significance & Outlook

The World Adhesive & Sealant Conference 2026 will play a vital role in shaping the future of the industry. The insights and networking opportunities provided will serve as a crucial foundation for participating companies to define new R&D directions, establish strategic partnerships, and overcome market challenges. Particularly, sustainable product development and the adoption of digital technologies are expected to be major drivers of future industry growth, with higher-performance and more environmentally friendly adhesive and sealant solutions accelerating innovation across various industrial sectors.

Source: <https://www.wac2026.org/>

#04 APPLIED Adhesives Acquires Dutch Van Asperen Kleefstoffen, Bolstering European Presence in Packaging & Labeling

Published August 06, 2026 PR Newswire USA



OVERVIEW

APPLIED Adhesives has strategically expanded its European footprint by acquiring Van Asperen Kleefstoffen, a Dutch adhesive solutions provider. This acquisition strengthens APPLIED's position in the packaging, labeling, and paper converting markets, enhancing its existing partnerships with industry giants like Henkel and 3M. The integration will allow APPLIED to offer enhanced technical support and a broader product portfolio to European customers, accelerating regional growth.

Key Findings

APPLIED Adhesives has successfully completed the acquisition of Van Asperen Kleefstoffen, a Netherlands-based specialist in adhesive solutions, significantly strengthening its operational base in the European market. This strategic move aims to expand APPLIED's presence particularly in key sectors such as packaging, labeling, and paper converting, thereby enhancing its service delivery capabilities to customers.

Technical & Business Details

Van Asperen Kleefstoffen brings extensive adhesive expertise and a robust customer network established across Europe, enabling APPLIED Adhesives to effectively broaden its market reach. Van Asperen also holds long-standing collaborations with industry leaders like Henkel and 3M, which APPLIED plans to leverage and further develop. This integration is expected to allow APPLIED to offer a diverse range of adhesive products coupled with specialized application knowledge to its European clientele.

Background & Context

The global adhesive market is experiencing growing demand across various industries including packaging, automotive, construction, and electronics, prompting companies to pursue strategic mergers and acquisitions to gain market share and expand their geographical presence. APPLIED Adhesives is actively pursuing an aggressive growth strategy, aiming to replicate its North American success in the European market. This acquisition represents a critical step in reinforcing its global supply chain and distribution network, enabling quicker and more effective responses to customer needs.

Strategic Significance & Outlook

Through the integration of Van Asperen Kleefstoffen, APPLIED Adhesives is poised to offer a wider product portfolio and enhanced technical support to its European customers. This acquisition is anticipated to boost the company's competitiveness in the European market and lay a strong foundation for future business expansion. The fusion of local expertise with global resources is expected to enable APPLIED to establish leadership in the European adhesive market.

Source: <https://www.prnewswire.com/news-releases/applied-adhesives-expands-european-presence-with-acquisition-of-van-asperen-kleefstoffen-302844575.html>

Collected: August 07, 2026 | Automated Research System (Gemini API)

#05 Henkel Raises 2026 Full-Year Sales Guidance as Adhesive Technologies Drives 4.5% Organic Growth

Published August 06, 2026 Henkel (公式プレスリリース) Germany



OVERVIEW

Henkel has significantly upgraded its 2026 full-year sales guidance, driven by robust H1 performance and a formidable 4.5% organic sales growth in its Adhesive Technologies business unit. This strong momentum, particularly a 7.8% organic sales surge in Mobility & Electronics, reflects escalating demand from EV and next-generation electronic devices. Strategic investments in smart factories and co-creation hubs, alongside successful M&A, position Henkel to capitalize on these high-growth sectors.

Background

The global demand for high-performance adhesives is experiencing continuous growth across critical sectors, including electronics, automotive, and packaging. This surge is particularly propelled by the rapid expansion of the electric vehicle (EV) market and the widespread proliferation of 5G and artificial intelligence (AI) powered devices. These advancements necessitate sophisticated bonding and sealing materials capable of delivering advanced functionalities such as superior heat resistance, enhanced electrical conductivity, lightweight properties, and exceptional durability. Recognizing these emerging trends early, Henkel has established itself as a technological leader, driving innovation and market introduction of advanced material solutions. With a globally integrated production system and a robust R&D network, the company demonstrates significant agility in responding to evolving regional and technological demands.

Key Findings

German chemical powerhouse Henkel reported a robust performance in the first half of 2026, leading to an upward revision of its full-year organic sales growth outlook. The Adhesive Technologies business unit served as a primary growth engine, achieving an impressive 4.5% organic sales growth and significantly contributing to the company's overall 3.2% organic sales increase. This exceptional performance from the adhesive division, coupled with its high profitability, was a major driver for Henkel's consolidated earnings.

A notable highlight within the Adhesive Technologies segment was the double-digit organic sales growth in the Mobility & Electronics business area, specifically a 7.8% increase. This strong indicator directly reflects the escalating demand for high-performance adhesives in electric vehicles and next-generation electronic devices. To further strengthen its competitive edge in this high-growth sector, Henkel is strategically investing in expanding its capabilities. Key initiatives include the construction of a new smart factory in China and the establishment of a co-creation hub in India, both aimed at accelerating the development and supply of innovative material solutions. Furthermore, targeted M&A activities within the Adhesive Technologies division positively impacted the first-half results.

Based on the sustained growth trajectory of its Adhesive Technologies division and solid performance across its diversified business portfolio, including consumer brands, Henkel has revised its full-year 2026 organic sales growth forecast to between 1.0% and 3.0%. The company remains committed to future investments in innovation, strategic M&A, and the establishment of highly efficient production systems to maintain and expand its global leadership. The Mobility & Electronics sector, identified as a high-growth area, is expected to be a pivotal revenue driver for Henkel's sustained future success.

Source: <https://www.henkel.com/press-and-media/press-releases-and-kits/2026-08-06-henkel-delivers-strong-sales-and-earnings-performance-in-the-first-half-and-upgrades-top-line-guidance-for-2026-2217762>

Collected: August 07, 2026 | Automated Research System (Gemini API)

#06 Indium Corporation Unveils Plating-Free Copper Sintering Paste and Bi-Free Mid-Temp Solder at ICEPT 2026

Published July 30, 2026 Indium Corporation USA



Reliable Copper Sintering Paste
eliminates need for gold or silver plating

Bismuth-Free Mid-Temperature Solder

OVERVIEW

Indium Corporation will present two significant advancements at ICEPT 2026: a next-generation copper sintering paste for high-power semiconductors and a lead-free, bismuth-free indium-containing mid-temperature solder for advanced electronics assembly. The copper sintering paste eliminates the need for gold or silver plating while delivering high reliability and strong bonds, promising cost reductions and process simplification. The novel solder addresses environmental regulations and high-performance requirements, ensuring reliability and sustainability for future electronic devices.

Key Findings

Indium Corporation is set to unveil significant advancements at ICEPT 2026 (International Conference on Electronic Packaging Technology), introducing a next-generation copper sintering paste for high-power semiconductor applications and a lead-free, bismuth (Bi)-free indium-containing mid-temperature solder for advanced electronics assembly.

These two industry-defining solutions aim to address critical challenges in semiconductor packaging and electronics manufacturing, balancing high performance with sustainability.

Technical & Business Details

The newly introduced copper sintering paste offers a crucial breakthrough in thermal management for high-power semiconductor devices. Traditionally, sintering processes required gold or silver plating for surface preparation; however, this novel material delivers high reliability and strong bonding strength without the need for such precious metal platings. This innovation is expected to lead to significant manufacturing cost reductions, process simplification, and improved supply chain efficiency. Concurrently, the lead-free and Bi-free indium-containing mid-temperature solder has been developed to meet stringent environmental regulations and the growing demand for high-performance electronics. This solder provides excellent joint reliability and thermal fatigue resistance while eliminating hazardous substances, thus contributing to sustainable electronics manufacturing. Its capability for mid-temperature processing minimizes thermal stress on sensitive components, enabling reliable bonding.

Background & Context

The modern electronics industry, particularly in semiconductor devices, is characterized by ongoing miniaturization, increased power output, and higher component density, making efficient thermal management and high-reliability bonding technologies indispensable. Furthermore, stricter environmental regulations are accelerating the shift towards more eco-friendly materials that are free of hazardous substances like lead and bismuth. Indium Corporation's new solutions directly address these market demands, promising significant value in sectors such as electric vehicles, renewable energy, 5G infrastructure, and AI-related hardware. The progression of next-generation packaging technologies will critically depend on the availability and performance of these advanced materials.

Strategic Significance & Outlook

These innovative materials announced by Indium Corporation are expected to play a pivotal role in shaping the future of semiconductor and electronics manufacturing. The plating-free copper sintering paste will contribute to improved performance and cost reduction for high-power devices, while the lead-free, Bi-free mid-temperature solder will ensure the reliability of next-generation electronic devices while reducing environmental impact. These technologies are poised to drive sustainability and technological evolution across the electronics industry and set new directions for future material development.

Source: <https://www.indium.com/press-releases/indium-corporation-to-present-advancements-in-two-industry-defining-solutions-at-icept-2026/>

#07 Sumitomo Bakelite Achieves Record ¥305 Billion Sales in FY2025 Driven by Advanced Encapsulants for AI Silicon

Published August 05, 2026 The Shashi (住友ベークライトの会社情報を含むサイト)
Japan



OVERVIEW

Sumitomo Bakelite Co., Ltd. has announced a record-high ¥305 billion (\$2.0 billion USD) in consolidated sales for FY2025, primarily propelled by a robust recovery and growth in its encapsulant materials business for advanced packaging, particularly for AI training silicon. The company's success stems from its strategic shift to application-focused solutions, providing high-performance materials like epoxy molding compounds that address critical challenges in the rapidly expanding AI and high-performance computing sectors.

Background

The rapid advancement of artificial intelligence (AI) technology in recent years has ignited an explosive demand for high-performance semiconductors, especially AI training chips. These advanced processors, characterized by increased heat generation and higher integration densities compared to conventional semiconductors, necessitate increasingly sophisticated encapsulation technologies. Material manufacturers like Sumitomo Bakelite are at the vanguard of this technological revolution, collaborating closely with semiconductor fabrication plants to engineer next-generation packaging solutions. Sumitomo Bakelite, a pioneer rooted in phenolic resins, boasts a long and distinguished history of supporting diverse industrial developments through materials science, having established itself as a leading innovator in semiconductor encapsulants within the electronics sector.

Key Findings

Sumitomo Bakelite Co., Ltd. reported a record-high consolidated sales figure of ¥305 billion (approximately \$2.0 billion USD) for the fiscal year ending March 2025. This significant achievement was primarily fueled by the robust recovery and substantial growth of its encapsulant materials business, with a particular emphasis on advanced packaging solutions tailored for AI training silicon.

Technical & Business Details

The company's encapsulant business specializes in delivering high-performance advanced materials, such as epoxy molding compounds, precisely engineered to meet the evolving demands of semiconductors used in AI and High-Performance Computing (HPC). These specialized materials are indispensable for enhancing semiconductor reliability, facilitating superior heat dissipation, enabling further miniaturization, and ensuring stable operation even under the most demanding environmental conditions. Sumitomo Bakelite's strategic approach transcends mere material provision; it emphasizes an "applications-first" philosophy, positioning the company as a comprehensive solutions provider. This strategy allows them to directly address and resolve challenges faced in customers' end products. By adopting this customer-centric approach, Sumitomo Bakelite has effectively captured the burgeoning demand for high-performance silicon packaging, which is crucial for advancing AI technology, thereby accelerating both product development cycles and market introduction.

Strategic Significance & Outlook

With the AI market projected for sustained and rapid expansion, Sumitomo Bakelite is committed to further strengthening its advanced semiconductor encapsulant business. The company plans to continuously introduce higher-performance and more reliable material solutions, achieved through ongoing collaborative development efforts with its customers. This unwavering commitment will ensure Sumitomo Bakelite continues to play a pivotal role in supporting the evolution of AI and HPC through cutting-edge material technology. This record-breaking sales performance is a clear testament to the efficacy of its strategic investments and technological development, laying a solid foundation for sustainable growth in the years to come.

Source: <https://the-shashi.com/en/tse/4203/>

#08 Univar Solutions Acquires H.M. Royal, Expanding Distribution of Rubber, Plastic, and Adhesive Additives Across US

Published August 03, 2026 Coatings World USA



OVERVIEW

Univar Solutions has strategically expanded its European footprint by acquiring Van Asperen Kleefstoffen, a Dutch adhesive solutions provider. This acquisition strengthens APPLIED's position in the packaging, labeling, and paper converting markets, enhancing its existing partnerships with industry giants like Henkel and 3M. The integration will allow APPLIED to offer enhanced technical support and a broader product portfolio to European customers, accelerating regional growth.

Key Findings

Univar Solutions has completed the acquisition of H.M. Royal, a specialized distributor of additives for rubber, plastics, and adhesives. This strategic acquisition significantly bolsters Univar Solutions' performance materials business, particularly expanding its distribution capabilities and value proposition in the adhesives and sealants sectors across the United States.

Technical & Business Details

H.M. Royal has long been a trusted partner in the high-performance rubber, plastics, and adhesive additives sectors. Its extensive product portfolio and specialized technical support have been highly valued by customers in diverse industries, including tire manufacturing, automotive, construction, and electronics. By integrating H.M. Royal's strengths with its own broad distribution network, Univar Solutions will be able to offer more comprehensive material solutions to its customers. This synergy of expertise and resources will enable deeper levels of customer support, ranging from adhesive and sealant formulation design to application assistance.

Background & Context

The distribution market for specialty chemicals and materials is experiencing accelerated demand for streamlined supply chains and enhanced technical support from customers. M&A has become a primary means for companies to expand their product offerings, extend their geographical reach, and deepen their specialization. As a key player in this industry, Univar Solutions has pursued strategic acquisitions as part of its continuous growth strategy. The acquisition of H.M. Royal is particularly significant in the anticipated growth of the adhesives and sealants market, cementing Univar Solutions' position and establishing a competitive advantage.

Strategic Significance & Outlook

Through the acquisition of H.M. Royal, Univar Solutions aims to further strengthen its leadership in the performance materials market. The combined entity will offer a more diverse range of products and specialized services across the rubber, plastics, and adhesives sectors, supporting customers in achieving their innovation and sustainability goals. This acquisition is expected to contribute to an expanded customer base, optimized product portfolio, and reinforced presence in the North American market, making it an integral component of Univar Solutions' long-term growth strategy.

Source: <https://www.coatingsworld.com/breaking-news/univar-solutions-acquires-h-m-royal/>

Collected: August 07, 2026 | Automated Research System (Gemini API)

#09 Emerson Acquires AI-Enabled Validation and Test Software Innovator Glue Inc. to Accelerate Software-Defined Strategy

Published August 06, 2026 StockTitan (PR Newswireの転載) USA



OVERVIEW

Emerson Electric Co. has acquired Glue Inc., a pioneering developer of AI-powered validation and test software, including its flagship "Glue Studio." This strategic move aims to significantly accelerate Emerson's software-defined, data-centric test and measurement strategy. The integration of Glue Inc.'s technology is set to infuse advanced AI capabilities into Emerson's test workflows, promising enhanced efficiency and accuracy for automation solutions across high-precision industries.

Background

The landscape of modern manufacturing is increasingly defined by escalating product complexity and compressed development cycles, demanding more sophisticated test and measurement solutions. The advent and evolution of artificial intelligence (AI) offer a transformative opportunity to drastically enhance efficiency and quality when integrated directly into the testing process. Furthermore, software-defined testing (SDT) allows for flexible configuration and modification of test environments through software, decoupling them from physical hardware constraints. This paradigm shift translates into reduced development costs and accelerated adaptation to market dynamics. Emerson has been proactively investing in innovation within this critical domain, and the acquisition of Glue Inc. represents a pivotal milestone in advancing this strategic imperative.

Key Findings

Emerson Electric Co. has completed the acquisition of Glue Inc., a highly innovative firm specializing in AI-powered validation and test software. This strategic maneuver is engineered to accelerate Emerson's ambitious software-defined, data-centric test and measurement strategy while solidifying its technological preeminence in the industry.

Central to Glue Inc.'s offering is "Glue Studio," its flagship AI-enabled validation and test software. This powerful platform is renowned for its ability to automate intricate test workflows and significantly enhance data analysis capabilities. By streamlining these critical processes, Glue Studio plays a pivotal role in shortening product development cycles, markedly improving test accuracy and efficiency, and ultimately empowering companies to accelerate time-to-market and ensure uncompromised product quality.

As a global vanguard in industrial automation and measurement technology, Emerson will seamlessly integrate Glue Inc.'s sophisticated AI capabilities into its expansive suite of test and measurement solutions. This integration will furnish Emerson's customers with a more intelligent and predictive testing ecosystem, substantially bolstering their competitive edge, especially within demanding, high-precision sectors like semiconductors, automotive, and aerospace.

The integration of Glue Inc.'s technology is poised to profoundly enhance AI capabilities across Emerson's entire test and measurement portfolio, generating substantial added value for its clientele. This acquisition strategically aligns with the ongoing evolution of Industrial IoT (IIoT) and digital twin technologies, unlocking new opportunities to derive actionable insights from test data. These insights can then be leveraged to optimize product design, refine manufacturing processes, and boost overall operational efficiency. Emerson's overarching objective is to empower its customers to accelerate innovation and deliver superior quality products to market through cutting-edge, AI-driven solutions. This integration is set to redefine the application and impact of AI within the test and measurement industry, establishing novel benchmarks for performance and intelligence.

Source: <https://www.stocktitan.net/news/EMR/emerson-acquires-glue-inc-to-accelerate-ai-driven-test-measurement-r1asp1gy83jl.html>

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#11 Dexerials Reports Solid Functional Materials Performance in Q1 2026, Accelerates Innovation with CIOE 2026 Exhibition and Office Renewal

Published August 04, 2026 Dexerials Corporation (公式ウェブサイト) Japan



OVERVIEW

Dexerials Corporation has reported strong Q1 FY2026 consolidated financial results, driven by steady demand for its high-performance functional materials, including Anisotropic Conductive Film (ACF) and Optical Elastic Resin (SVR), across key sectors like smartphones and automotive electronics. The company is simultaneously intensifying its innovation efforts by participating in CIOE 2026 to expand its global customer base and transforming its Tokyo office into an "Empower Synergy Office" to foster internal collaboration and idea generation.

Background

The global electronics market is experiencing continuous growth, driven by the proliferation of new technologies such as 5G, IoT, and AI. This trend is increasing demand for higher functionality, miniaturization, and improved reliability in electronic components, amplifying the importance of advanced functional materials like those supplied by Dexerials. Particularly, the evolution of in-vehicle electronics is driving demand for material solutions that offer reliability under more stringent environmental conditions. Dexerials addresses these market trends by focusing on strengthening R&D and production capabilities, thereby establishing a competitive advantage in the market.

Key Findings

Dexerials Corporation announced its consolidated financial results for the first quarter ending June 30, 2026, revealing that its key functional materials businesses maintained robust performance. The company continues to meet market demand by supplying high-performance materials such as Anisotropic Conductive Film (ACF), Optical Elastic Resin (SVR), and industrial adhesives for growing sectors like smartphones and automotive electronics.

As a global leader in the development, manufacturing, and sales of electronic bonding materials, optical materials, and other functional materials, Dexerials' flagship Anisotropic Conductive Film (ACF) is critical for compact, high-density packaging in displays and camera modules, enhancing the performance of smartphones and tablets. Its Optical Elastic Resin (SVR) is increasingly adopted in automotive displays for improved visibility and impact resistance, while industrial adhesives offer versatile bonding solutions across a wide array of industrial sectors.

Furthering its commitment to innovation and co-creation, Dexerials will exhibit at the China International Optoelectronic Exposition (CIOE 2026) in Shenzhen. This strategic move aims to expand its customer base in the crucial Chinese market and showcase its latest technologies. Domestically, the company has refurbished its Tokyo office into an 'Empower Synergy Office,' fostering an environment designed to strengthen employee collaboration and spark new ideas. These initiatives underscore Dexerials' investment in corporate culture and environmental development to support continuous technological innovation. Additionally, the completion of payment for restricted stock as compensation was announced, reflecting an IR strategy to motivate management and employees and enhance shareholder value.

Looking ahead, Dexerials will continue to strengthen its R&D investments, prioritizing the development of next-generation functional materials. Significant performance enhancements for ACFs and SVRs, along with their expansion into new application areas, are particularly anticipated. Active participation in global exhibitions and the cultivation of an internal innovation environment are crucial strategies for the company to adapt swiftly to market changes and achieve sustainable growth. Through these concerted efforts, Dexerials aims to maintain its leadership in technological innovation within the electronic components industry.

Source: <https://www.dexerials.jp/en/>

#13 Resonac and QC Ware Collaboration Achieves 28x Speedup in Chemical Reaction Transition State Calculations, Dramatically Enhancing Semiconductor Material Development Efficiency

Published August 04, 2026 Resonac (公式ウェブサイト) Japan



OVERVIEW

In a significant breakthrough for materials science, Resonac, partnering with QC Ware, has validated a next-generation computational chemistry technology that accelerates chemical reaction transition state calculations by an astounding 28 times compared to conventional methods. This dramatic speedup is set to revolutionize the development of critical materials, particularly for semiconductors, by drastically shortening the discovery and optimization cycles, thereby promising substantial industrial impact.

Background

The field of materials science is undergoing a rapid paradigm shift, moving away from traditional experimental "trial and error" methodologies towards "materials informatics." This data-driven approach leverages advanced computational science for highly efficient material design and discovery. While powerful computational methods, including quantum chemistry calculations and molecular dynamics simulations, have become indispensable tools for new material development, their inherent computational intensity has historically presented a significant bottleneck. Overcoming this challenge and accelerating the digital transformation of materials development necessitates strategic collaborations with pioneers in advanced computing, such as QC Ware, a leader in quantum computing software. For Resonac, a global leader with diverse interests spanning semiconductor materials, automotive components, and infrastructure, strengthening foundational computational chemistry technologies is paramount to enhancing its competitive edge across all business domains.

Key Findings

Resonac, in a collaborative effort with quantum computing software developer QC Ware, has successfully validated a groundbreaking next-generation computational chemistry technology. This innovation dramatically accelerates the calculation of chemical reaction transition states by approximately 28 times compared to conventional standard methods. Transition state calculations are fundamental to deciphering chemical reaction pathways and energy barriers, making them indispensable for the design of novel materials and the development of catalysts. Historically, these calculations have been exceptionally computationally intensive, demanding extensive resources and time, even when utilizing traditional supercomputers. This 28-fold acceleration directly translates into a profound enhancement in the efficiency of real-world material development processes, with particularly significant implications for semiconductor materials.

Technical Deep Dive & Industrial Impact

The validated next-generation computational chemistry technology developed through the Resonac and QC Ware collaboration effectively addresses the critical bottleneck of high computational cost. It achieves this breakthrough through a synergistic combination of advanced algorithms and optimized utilization of computational resources. The approximate 28-fold speedup is transformative, implying that calculations that once consumed weeks or even months can now be completed in mere days or even hours. This significantly enhanced computational throughput empowers researchers to explore an exponentially larger number of candidate compounds and intricate reaction pathways, leading to a much faster identification of optimal material solutions.

The industrial implications are particularly profound for semiconductor material development. As the industry continually pushes the boundaries of miniaturization and performance enhancement, even subtle variations in material composition or structural properties can critically influence the final product's functionality and reliability. By applying this accelerated computational technology, Resonac anticipates a significant speedup in the discovery and evaluation processes for crucial semiconductor components, including novel dielectric materials, advanced interconnects, and high-performance encapsulants. This acceleration will directly contribute to reduced time-to-market for new semiconductor products, thereby bolstering the competitiveness of semiconductor manufacturing.

Strategic Significance & Outlook

These validation results mark a pivotal achievement for Resonac, significantly advancing the digital transformation of real-world material development in alignment with its corporate vision to "change society through chemistry." The successful collaboration with QC Ware establishes a clear pathway for the practical application of quantum computing and other advanced computational chemistry paradigms to pressing industrial challenges. Looking ahead, it is anticipated that similar acceleration technologies could extend their impact far beyond the semiconductor sector, finding critical applications in the development of next-generation battery materials, high-efficiency catalysts, and advanced polymer compounds. The widespread adoption of this technology promises to dramatically shorten the entire cycle from novel material discovery to practical industrial application, thereby making a substantial contribution to the realization of a more sustainable society.

Source: <https://www.resonac.com/>

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